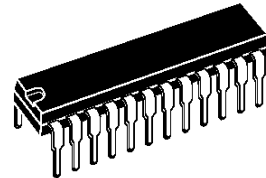


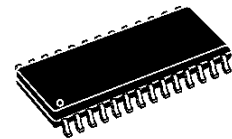
**BUS-CONTROLLED AUDIO MATRIX**

- 6 STEREO INPUTS
- 3 STEREO OUTPUTS
- GAIN CONTROL 0dB/MUTE FOR EACH OUTPUT
- CASCADABLE (2 DIFFERENT ADDRESSES)
- SERIAL BUS CONTROLLED
- VERY LOW NOISE
- VERY LOW DISTORSION
- FULLY ESD PROTECTED



**SHRINK 24**  
(Plastic Package)

**ORDER CODE : TEA6422**



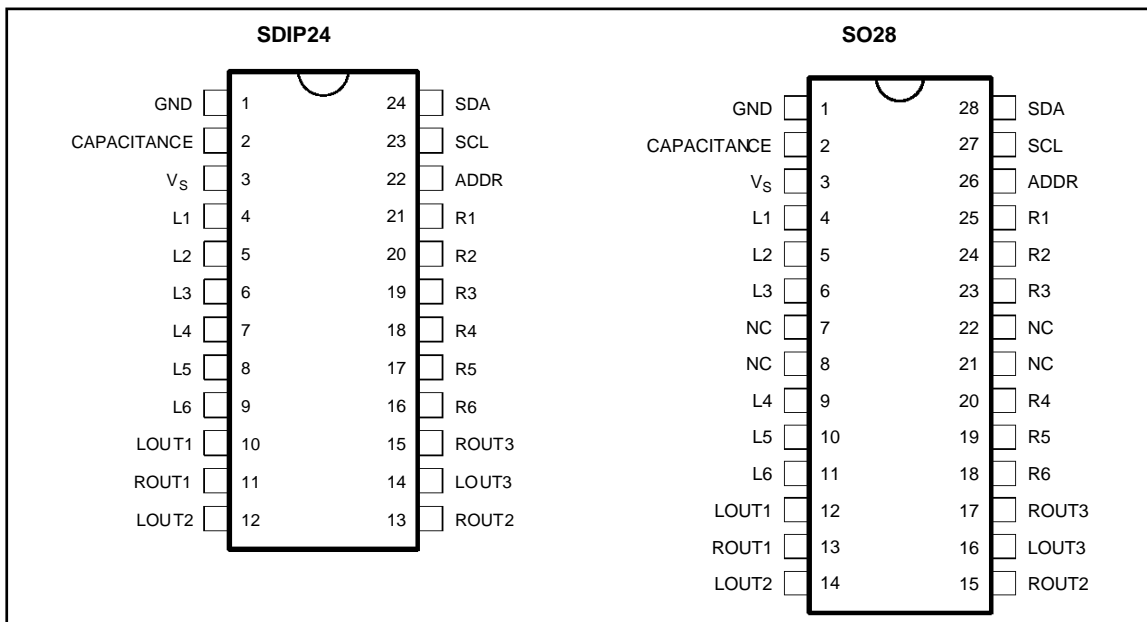
**SO28**  
(Plastic Micropackage)

**ORDER CODE : TEA6422D**

**DESCRIPTION**

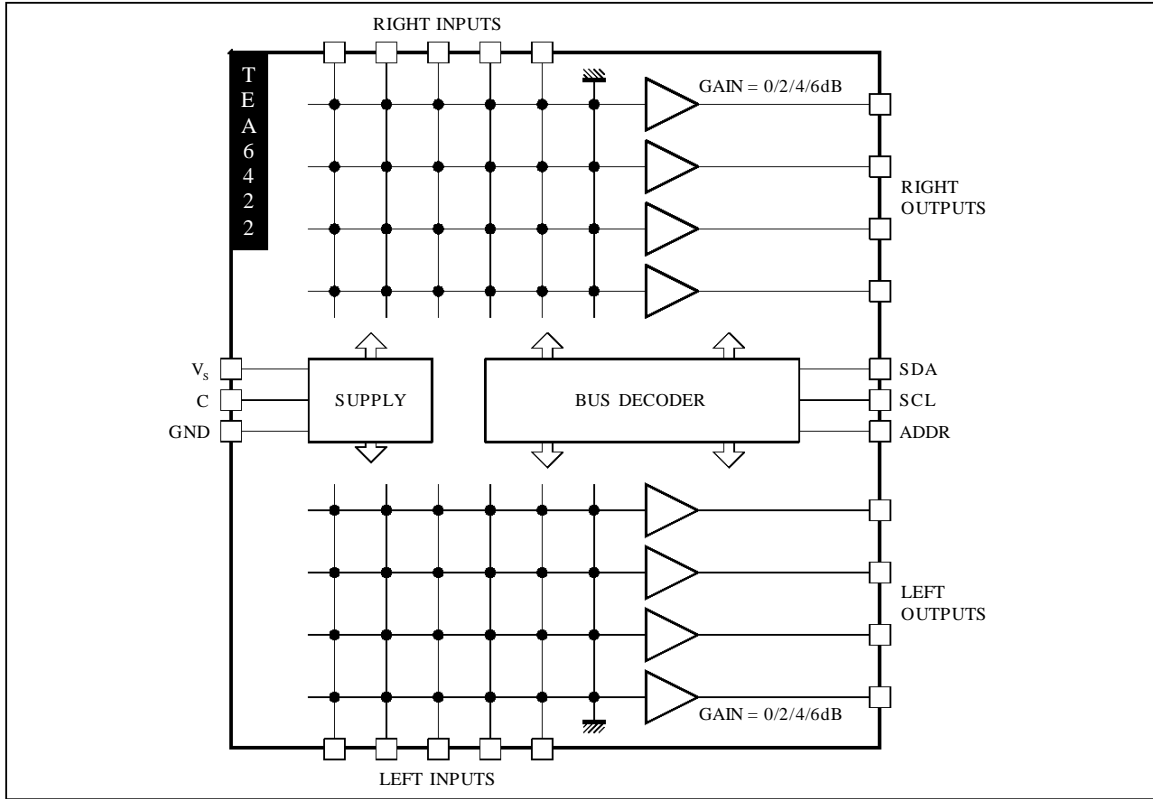
The TEA6422 switches 6 stereo audio inputs on 3 stereo outputs.  
All the switching possibilities are changed through the I<sup>2</sup>C BUS.

**PIN CONNECTIONS**



6422-01.EPS / 6422-02.EPS

**BLOCK DIAGRAM**



6422-03.EPS

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply Voltage	12	V
T <sub>oper</sub>	Operating Temperature	0, + 70	°C
T <sub>stg</sub>	Storage Temperature	- 20, + 150	°C

6422-01.TBL

**THERMAL DATA**

Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction - ambient Thermal Resistance	SDIP24 75	°C/W
		SO28 75	°C/W

6422-02.TBL

**ELECTRICAL CHARACTERISTICS**

$T_A = 25^{\circ}\text{C}$ ,  $V_S = 9\text{V}$ ,  $R_L = 10\text{k}\Omega$ ,  $R_G = 600\Omega$ ,  $f = 1\text{kHz}$  (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
--------	-----------	-----------------	------	------	------	------

**SUPPLY**

$V_S$	Supply Voltage		8	9	10.2	V
$I_S$	Supply Current			3	8	mA
SVR	Ripple Rejection	$V_{IN} = 500\text{mV}_{\text{RMS}}$ , $f = 1\text{kHz}$	70	80		dB

**MATRIX**

$V_{IN}$	Input DC Level			4.5		V
$R_I$	Input Resistance		30	50	100	$\text{k}\Omega$
$C_S$	Channel Separation	$V_{IN} = 2V_{\text{RMS}}$ , $f = 1\text{kHz}$	80	90		dB

**OUTPUT BUFFER**

$V_{OUT}$	Output DC Level		4.2	4.5	4.8	V
$R_{OUT}$	Output Resistance			50	100	$\Omega$
$e_{NI}$	Input Noise	$BW = 20 - 20\text{kHz}$ , flat		3		$\mu\text{V}$
S/N	Signal to Noise Ratio	$V_{IN} = V_{OUT} = 1V_{\text{RMS}}$		110		dB
G	Gain		-1	0	+ 1	dB
d	Distortion	$V_{IN} = V_{OUT} = 1V_{\text{RMS}}$		0.01	0.05	%
$V_{CL}$	Clipping Level	$d = 0.3\%$	2	2.5		$V_{\text{RMS}}$
$R_L$	Output Load Resistance		2			$\text{k}\Omega$

6422-03.TBL

**I<sup>2</sup>C BUS CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
SCL					
V <sub>IL</sub>	Low Level Input Voltage		- 0.3	+ 1.5	V
V <sub>IH</sub>	High Level Input Voltage		3.0	V <sub>CC</sub> + 0.5	V
I <sub>LI</sub>	Input Leakage Current	V <sub>I</sub> = 0 to V <sub>CC</sub>	- 10	+ 10	μA
f <sub>SCL</sub>	Clock Frequency		0	100	kHz
t <sub>R</sub>	Input Rise Time	1.5V to 3V		1000	ns
t <sub>F</sub>	Input Fall Time	1.5V to 3V		300	ns
C <sub>I</sub>	Input Capacitance			10	pF

SDA

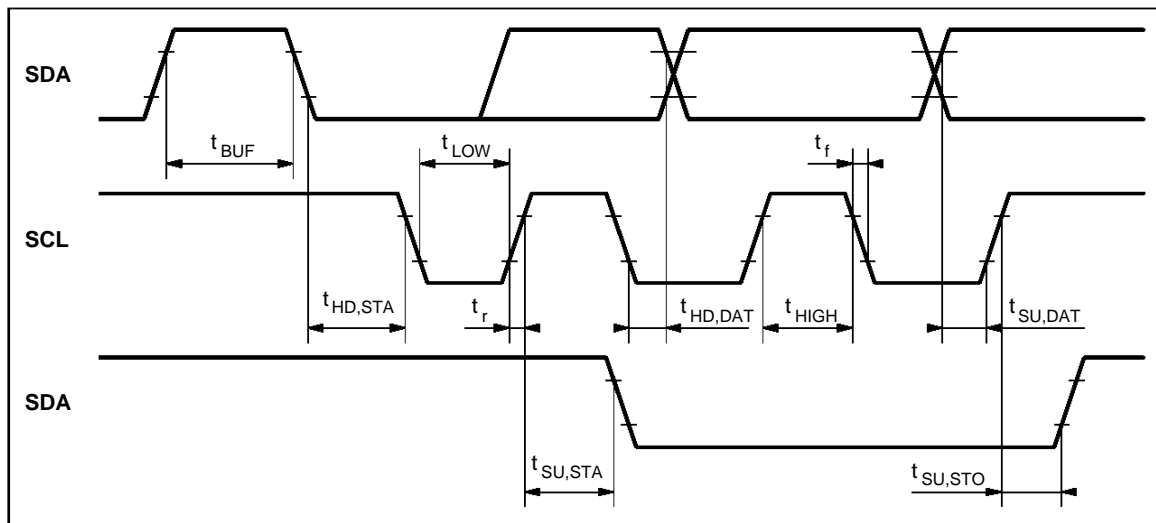
V <sub>IL</sub>	Low Level Input Voltage		- 0.3	+ 1.5	V
V <sub>IH</sub>	High Level Input Voltage		3.0	V <sub>CC</sub> + 0.5	V
I <sub>LI</sub>	Input Leakage Current	V <sub>I</sub> = 0 to V <sub>CC</sub>	- 10	+ 10	μA
C <sub>I</sub>	Input Capacitance			10	pF
t <sub>R</sub>	Input Rise Time	1.5V to 3V		1000	ns
t <sub>F</sub>	Input Fall Time	1.5V to 3V		300	ns
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OL</sub> = 3mA		0.4	V
t <sub>F</sub>	Output Fall Time	3V to 1.5V		250	ns
C <sub>L</sub>	Load Capacitance			400	pF

TIMING

t <sub>LOW</sub>	Clock Low Period		4.7		μs
t <sub>HIGH</sub>	Clock High Period		4.0		μs
t <sub>SU, DAT</sub>	Data Set-up Time		250		ns
t <sub>HD, DAT</sub>	Data Hold Time		0	340	ns
t <sub>SU, STO</sub>	Set-up Time from Clock High to Stop		4.0		μs
t <sub>BUF</sub>	Start Set-up Time following a Stop		4.7		μs
t <sub>HD, STA</sub>	Start Hold Time		4.0		μs
t <sub>SU, STA</sub>	Start Set-up Time following Clock Low-to High Transition		4.7		μs

6422-04.TEL

**Figure 1 : I<sup>2</sup>C Bus Timing**



6422-04.EPS

**POWER ON RESET**

After power-on reset all outputs are in mute mode

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Reset	Start of Reset	Incr. V <sub>CC</sub>			2.5	V
	End of Reset	Decr. V <sub>CC</sub> Incr. V <sub>CC</sub>	4.5		4.2	V

6422-05.TBL

**SOFTWARE SPECIFICATION****1. Chip address**

Address	HEX	ADDR
1001 1000	98	0
1001 1010	9A	1

**2. Data bytes**

Output select

X	0	0	X	X	I <sub>2</sub>	I <sub>1</sub>	I <sub>0</sub>	Output 1 Output 2 Output 3
	0	1						
	1	0						

Input select

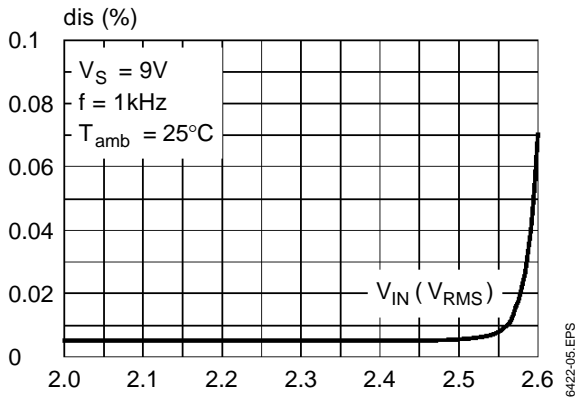
X	Q <sub>1</sub>	Q <sub>0</sub>	X	X	0	0	0	Input 1 Input 2 Input 3 Input 4 Input 5 Input 6 Mute
					0	0	0	
					0	0	1	
					0	1	0	
					0	1	1	
					1	0	0	
					1	0	1	
					1	1	0	

6422-06.TBL

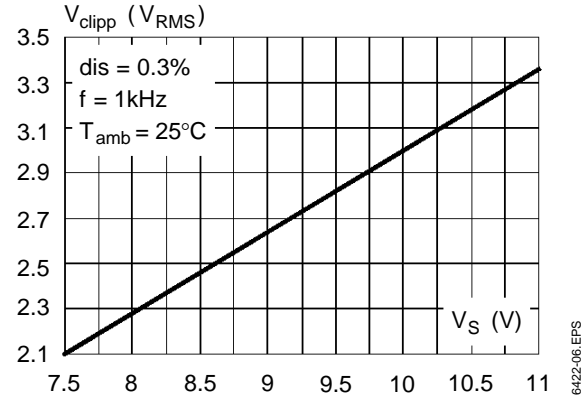
X = don't care - MSB is transmitted first

**Example** : 0 10 XX 100 connects outputs 3 with input 5.

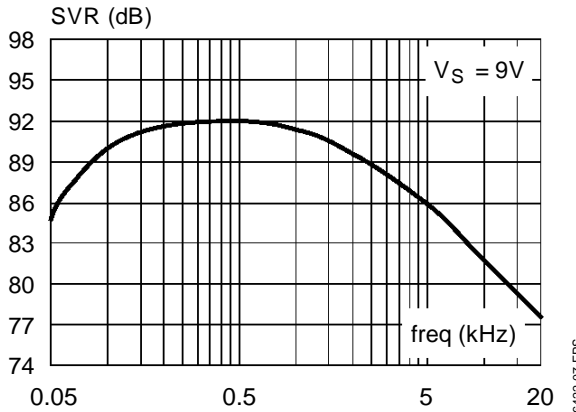
**Figure 2 :** Distorsion Level versus Input Voltage



**Figure 3 :** Clipping Level versus Supply Voltage

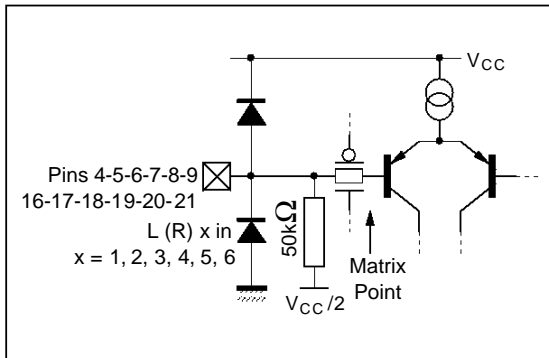


**Figure 4 :** Supply Voltage Rejection versus frequency ( $V_{IN} = 500mV_{RMS}$ )



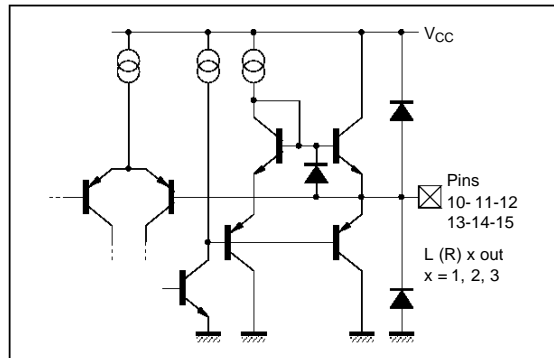
**PIN CONFIGURATIONS (SDIP24 Package)**

**Figure 5 : Audio IN**



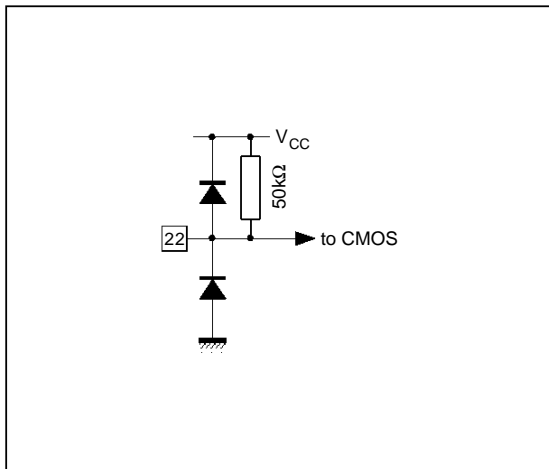
6422-08.EPS

**Figure 6 : Audio OUT**



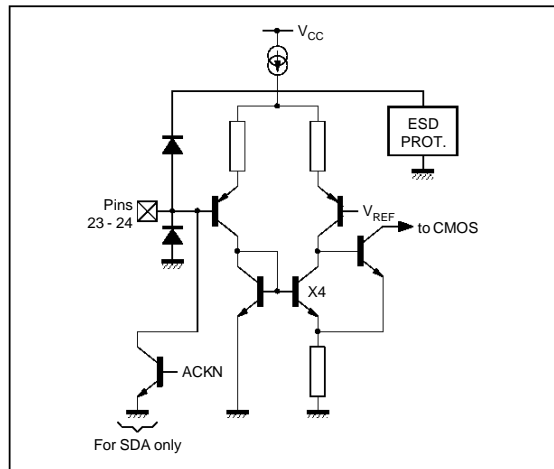
6422-08.EPS

**Figure 7 : ADDR**



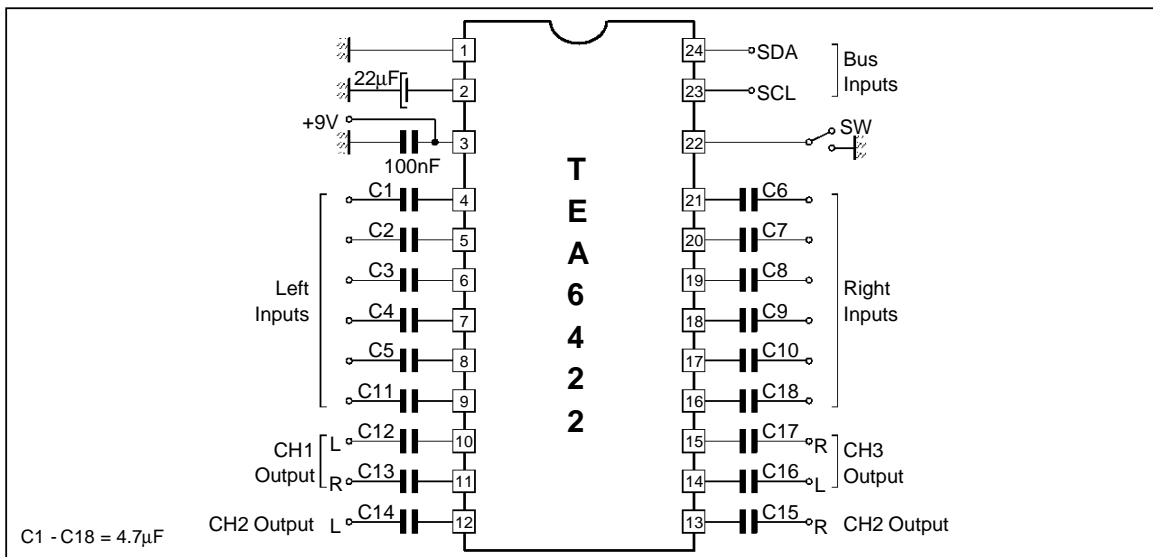
6422-10.EPS

**Figure 8 : Bus Inputs (SDA, SCL)**



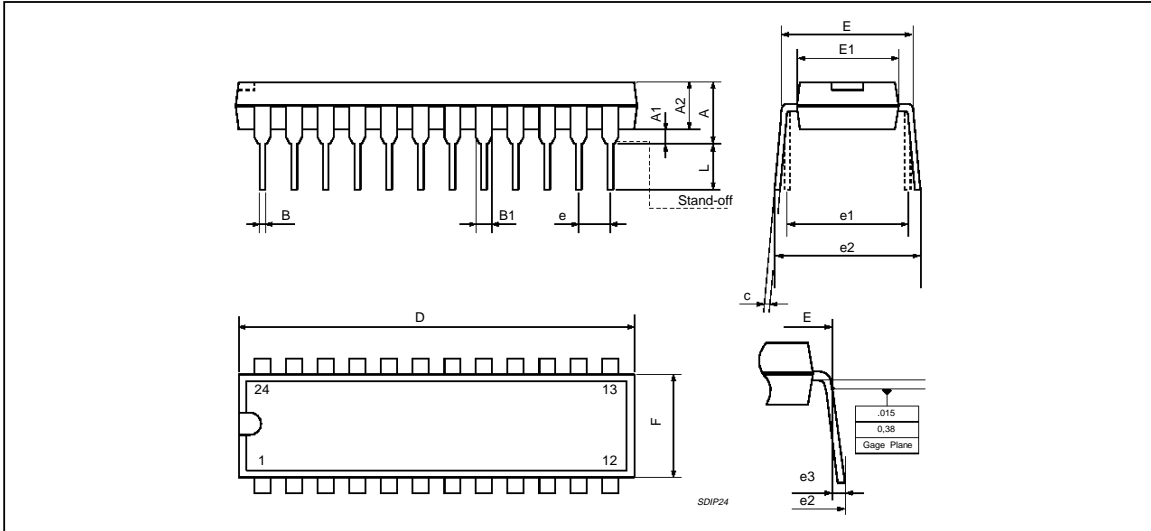
6422-11.EPS

**TYPICAL APPLICATION (SDIP24 Package)**



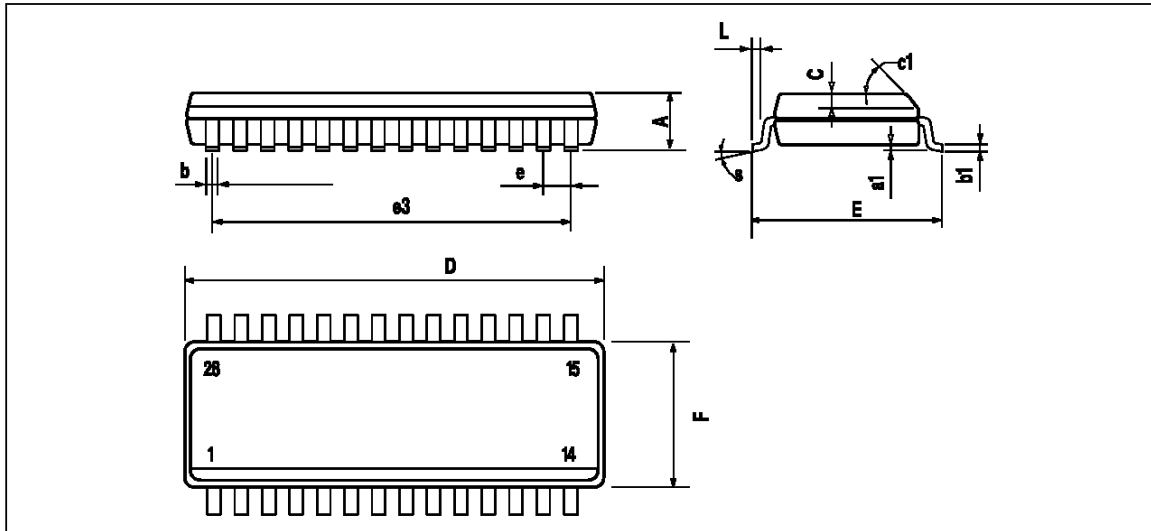
6422-12.EPS

**PACKAGE MECHANICAL DATA**  
24 PINS - PLASTIC SHRINK



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.08			0.20
A1	0.51			0.020		
A2	3.05	3.30	4.57	0.120	0.130	0.180
B	0.36	0.46	0.56	0.0142	0.0181	0.0220
B1	0.76	1.02	1.14	0.030	0.040	0.045
C	0.23	0.25	0.38	0.0090	0.0098	0.0150
D	22.61	22.86	23.11	0.890	0.90	0.910
E	7.62		8.64	0.30		0.340
E1	6.10	6.40	6.86	0.240	0.252	0.270
e		1.778			0.070	
e1		7.62			0.30	
e2			10.92			0.430
e3			1.52			0.060
L	2.54	3.30	3.81	0.10	0.130	0.150

**PACKAGE MECHANICAL DATA**  
28 PINS - PLASTIC MICROPACKAGE (SO)



P1M-SO28-EPS

Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			2.65			0.104
a1	0.1		0.3	0.004		0.012
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
C		0.5			0.020	
c1	45° (Typ.)					
D	17.7		18.1	0.697		0.713
E	10		10.65	0.394		0.419
e		1.27			0.050	
e3		16.51			0.65	
F	7.4		7.6	0.291		0.299
L	0.4		1.27	0.016		0.050
S	8° (Max.)					

SO28.TBL

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